WONDERLITE PC-6610

PC — CHIMEI Corporation

Processing/Physical Characteristics	Value	Unit	Test Standard
ISO Data			
Melt volume-flow rate, MVR	**10**	cm³/10min	ISO 1133
Temperature	**300**	°C	-
Load	**1.2**	kg	-
Molding shrinkage, parallel	**0.5**	%	ISO 294-4, 2577

Mechanical properties	Value	Unit	Test Standard
ISO Data			
Yield stress	**60**	MPa	ISO 527
Stress at break	**70**	MPa	ISO 527
Flexural modulus, 23°C	**2300**	MPa	ISO 178
Flexural strength	**90**	MPa	ISO 178
Charpy notched impact strength, +23°C	**60**	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	**15**	kJ/m²	ISO 179/1eA
Izod notched impact strength, +23°C	**60**	kJ/m²	ISO 180/1A
Izod notched impact strength	**15**	kJ/m²	ISO 180/1A
Temperature	**-30**	°C	-

Thermal properties	Value	Unit	Test Standard
ISO Data			
Temp. of deflection under load, 1.80 MPa	**125**	°C	ISO 75-1/-2
Vicat softening temperature, A	**150**	°C	ISO 306
Vicat softening temperature, B	**145**	°C	ISO 306
Coeff. of linear therm. expansion, parallel	**67**	E-6/K	ISO 11359-1/-2
Burning behav. at 1.5 mm nom. thickn.	**V-0**	class	IEC 60695-11-10
Thickness tested	**1.5**	mm	-
Yellow Card available	**yes**	-	-
Burning behav. 5V at thickness h	**5VA**	class	IEC 60695-11-20
Thickness tested	**3.0**	mm	-
Yellow Card available	**yes**	-	-

Electrical properties	Value	Unit	Test Standard
ISO Data			
Relative permittivity, 1MHz	**3**	-	IEC 62631-2-1
Volume resistivity	**3.6E14**	Ohm*m	IEC 62631-3-1
Surface resistivity	**9.3E14**	Ohm	IEC 62631-3-2

Other properties	Value	Unit	Test Standard
Density	**1200**	kg/m³	ISO 1183

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	**120**	°C	-
Pre-drying - Time	**4**	h	-
Mold temperature	**70 - 120**	°C	-
Feed temperature	**230 - 300**	°C	-
Zone 1	**250 - 320**	°C	-
Nozzle temperature	**250 - 310**	°C	-

Characteristics

Processing
Injection Molding

Applications
Electrical and Electronical

Special Characteristics
Flame retardant, Halogen-free, U.V. stabilized or stable to weather, Opaque

Regional Availability
Asia Pacific